



FINAL PRODUCT/PROCESS CHANGE NOTIFICATION
Generic Copy

01-Sep-2005

SUBJECT: ON Semiconductor Final Product/Process Change Notification #15011

TITLE: Seremban Assembly/Test Site Addition for Analog High Frequency 3x3 16-Lead QFN Package

EFFECTIVE DATE: 01-Nov-2005

AFFECTED CHANGE CATEGORY(S): ON Semiconductor Assembly and Test Site

AFFECTED PRODUCT DIVISION(S): Analog Power Products

ADDITIONAL RELIABILITY DATA: Available

Contact your local ON Semiconductor Sales Office or Matt Kas <fft7yg@onsemi.com>

SAMPLES: Contact your local ON Semiconductor Sales Office

FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:

Contact your local ON Semiconductor Sales Office or John Veto <rtrtd61@onsemi.com>

NOTIFICATION TYPE:

Final Product/Process Change Notification (FPCN)

Final change notification sent to customers. FPCNs are issued at least 60 days prior to implementation of the change.

ON Semiconductor will consider this change approved unless specific conditions of acceptance are provided in writing within 30 days of receipt of this notice. To do so, contact your local ON Semiconductor Sales Office.

DESCRIPTION AND PURPOSE:

This is an FPCN to IPCN 13296 available at www.onsemi.com

ON Semiconductor is pleased to announce the qualification of the ON Semiconductor Seremban facility located in Seremban, Malaysia to assemble and test the listed Analog High Frequency products in the 16 Lead 3x3 QFN package. Currently, the listed devices are manufactured and tested by ASAT (Hong Kong and China). There will be no changes in device functionality. Reliability will continue to meet or exceed ON Semiconductor's highest standards.

**Final Product/Process Change Notification #15011****RELIABILITY DATA SUMMARY:**

The following reliability results are for Seremban (SBN) 3X3 QFN Package, NCP1422 device.

Reliability Test Results:

Test	Conditions	Results
HTOL	TA=125°C, 504 hrs	0/231
HTB	TA=150°C, 1008 hrs	0/231
Preconditioning(PC)	MSL 1, 260° C	0/693
PC -Temp Cycle	-65/+150°C for 1000 cycles	0/231
PC -Autoclave	121°C/100%RH/15psig for 96hrs	0/231
PC -HAST	131°C/80%RH for 96 hrs	0/231
Solder Heat	260°C 10 seconds	0/90
Physical Dim. Case Outline		0/30
Wire Pull Per Factory		0/30, Cpk >1.33
Ball Shear Per Factory		0/30, Cpk >1.33
Die Shear Per Factory		0/30, Cpk >1.33
Solderability	Per Jedec	0/135

ELECTRICAL CHARACTERISTIC SUMMARY:

All product performance meets current datasheet specifications. Data is available upon request.

CHANGED PART IDENTIFICATION:

Assembly/Test location code in date code marking will change from "9" to "R".



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AFFECTED DEVICE LIST

PART

NB4L16MMN
NB4L16MMNR2
NB4L16MMNG
NB4L16MMNR2G
NB4N527SMN
NB4N527SMNR2
NB4N527SMNG
NB4N527SMNR2G
NB6L239MN
NB6L239MNR2
NB6L239MNG
NB6L239MNR2G
NB6N239SMN
NB6N239SMNR2
NB6N239SMNG
NB6N239SMNR2G
NB7L11MMN
NB7L11MMNR2
NB7L11MMNG
NB7L11MMNR2G
NB7L14MMN
NB7L14MMNR2
NB7L14MMNG
NB7L14MMNR2G
NB7L216MN
NB7L216MNR2
NB7L216MNG
NB7L216MNR2G
NB7L32MMNG
NB7L32MMNR2G
NB7L86MMN
NB7L86MMNR2
NB7L86MMNG
NB7L86MMNR2G
NBSG11MN
NBSG11MNR2
NBSG11MNG
NBSG11MNR2G
NBSG14MN
NBSG14MNR2
NBSG14MNG
NBSG14MNR2G
NBSG16MMN
NBSG16MMNR2
NBSG16MMNG
NBSG16MMNR2G



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NBSG16MN
NBSG16MNR2
NBSG16MNG
NBSG16MNR2G
NBSG16RMN
NBSG16RMNR2
NBSG16VSMN
NBSG16VSMNR2
NBSG16VSMNG
NBSG16VSMNR2G
NBSG53AMN
NBSG53AMNR2
NBSG53AMNG
NBSG53AMNR2G
NBSG72AMN
NBSG72AMNR2
NBSG72AMNG
NBSG72AMNR2G
NBSG86AMN
NBSG86AMNR2
NBSG86AMNG
NBSG86AMNR2G